

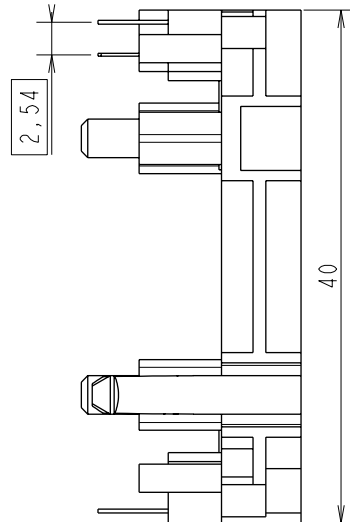
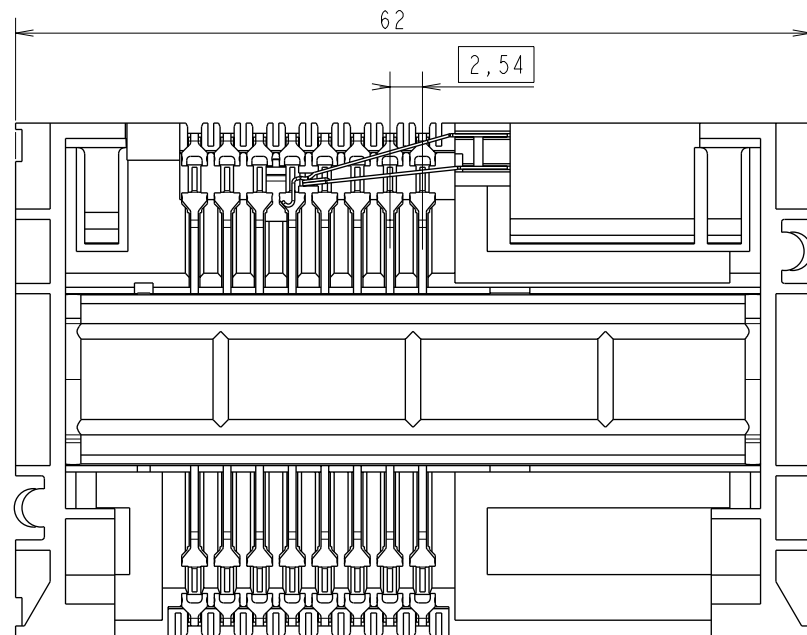
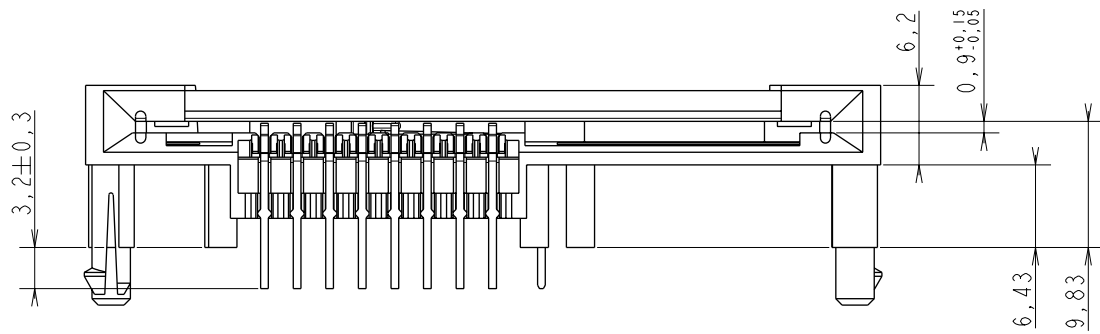
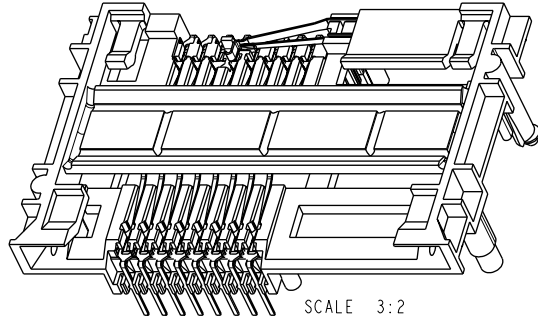
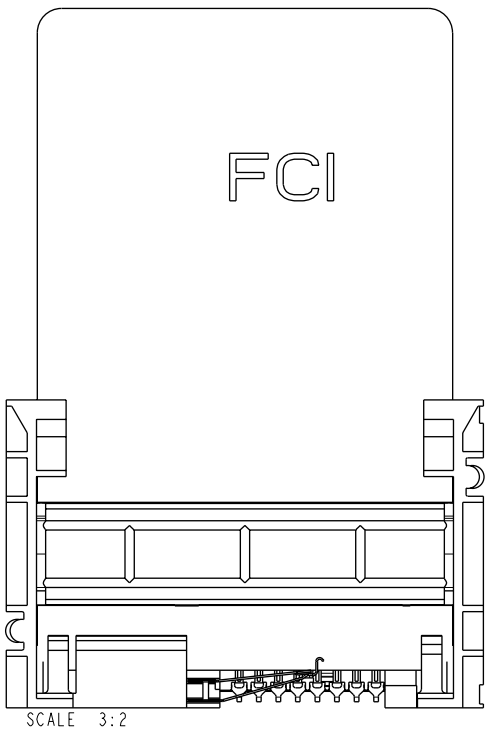
7334L2622F13LF

Lead Free Version (Optional)

Durability
 0: 2500 Mating Cycles
 2: 10000 Mating Cycles
 5: 100000 Mating Cycles

Number of contacts :
 2: 8 contacts ISO
 3: 16 contacts ISO + AFNOR

SCALE 3:2



General Tolerances: ± 0.2 mm

GENERAL:
 This L26 connector uses a "sliding" contact technology suitable for most applications.
 It has been designed for easy mounting on the PCB.

ELECTRICAL PROPERTIES:
 Insulation resistance : 5000 MΩ min
 Dielectric withstanding : 750 Vrms min
 Current carrying capacity : 10µA min. 1A max
 Contact resistance : 100mΩ max
 Card sensor type : Normally closed

MECHANICAL PROPERTIES:
 Contact Normal force : 0.6 N max (EMV Standard)
 Insertion force : 10 N max
 Extraction force : 1 N min

MATERIAL:
 Housing : Thermoplastic, Colour Black, Rated UL94V0
 Contacts and switch : Copper Alloy
 Plating : Gold over Nickel on contact area
 Matte Tin over Nickel on solder tails
 Bare edge allowed

ENVIRONMENT:
 Operating temperature: -20°C / +70°C
 Storage temperature: -40°C / +85°C
 Printed Circuit Board thickness : 1.6mm

REFERENCE DOCUMENTS:
 Product specification VGN 11596
 Packaging Specification VGN 11619

LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-22-008"

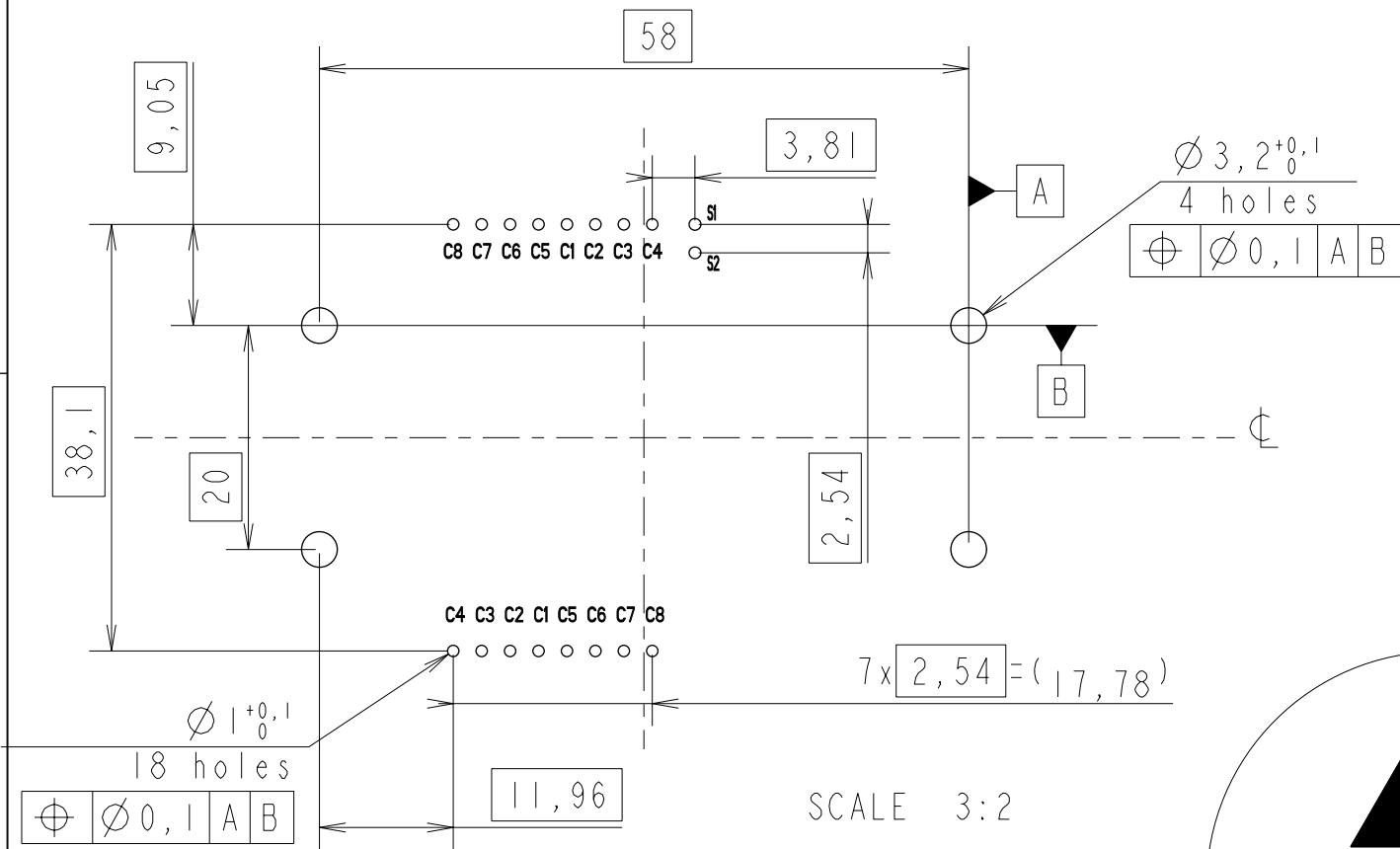
The housing will withstand exposure to 260°C peak temperature for 10seconds in a wave solder application with a 1.6mm minimum thick circuit board. Use protective adhesive tape (Kapton or Teflon) or protective metallic devices on the areas which are directly exposed to wave soldering as it is used in classical leaded wave soldering

EUROPEAN PROJECTION

www.fciconnect.com		surface - ✓	tolerance std ISO 1302	ISO 406	ISO 1101	projection	mm
		TOLERANCES UNLESS OTHERWISE SPECIFIED				⊕	←
Dr	N. TWINCY	2002/04/30	ANGULAR	0.X	±	size A2	Scale 5:2
Eng	F. TISSERAND	2002/04/30	LINEAR	0.XX	±	ECN 109-0057	
Chr	RAMESH.P.K	2009/04/15	0° ±°	0.XXX	±	Spec ref SEE NOTES	
Appr	S.S.CHERIAN	2009/04/15	Product family	SMART CARDS			
litr	ecn no	dr	date				
A	F20307	DLE	2002/04/30				
B	LS 3053	JTA	2003/05/13				
C	105-0071	DTK	2005/05/10				
D	106-0084	SSC	2006/06/21				
E	106-0183	SSC	2006/10/05				
F	109-0057	SSC	2009/04/15				
-	-	-	-				
FCI		L26 TYPE F13		dwg no	VJW_54825		
				Rev.	F		
		catalog no		See Table		sheet 1 of 2	

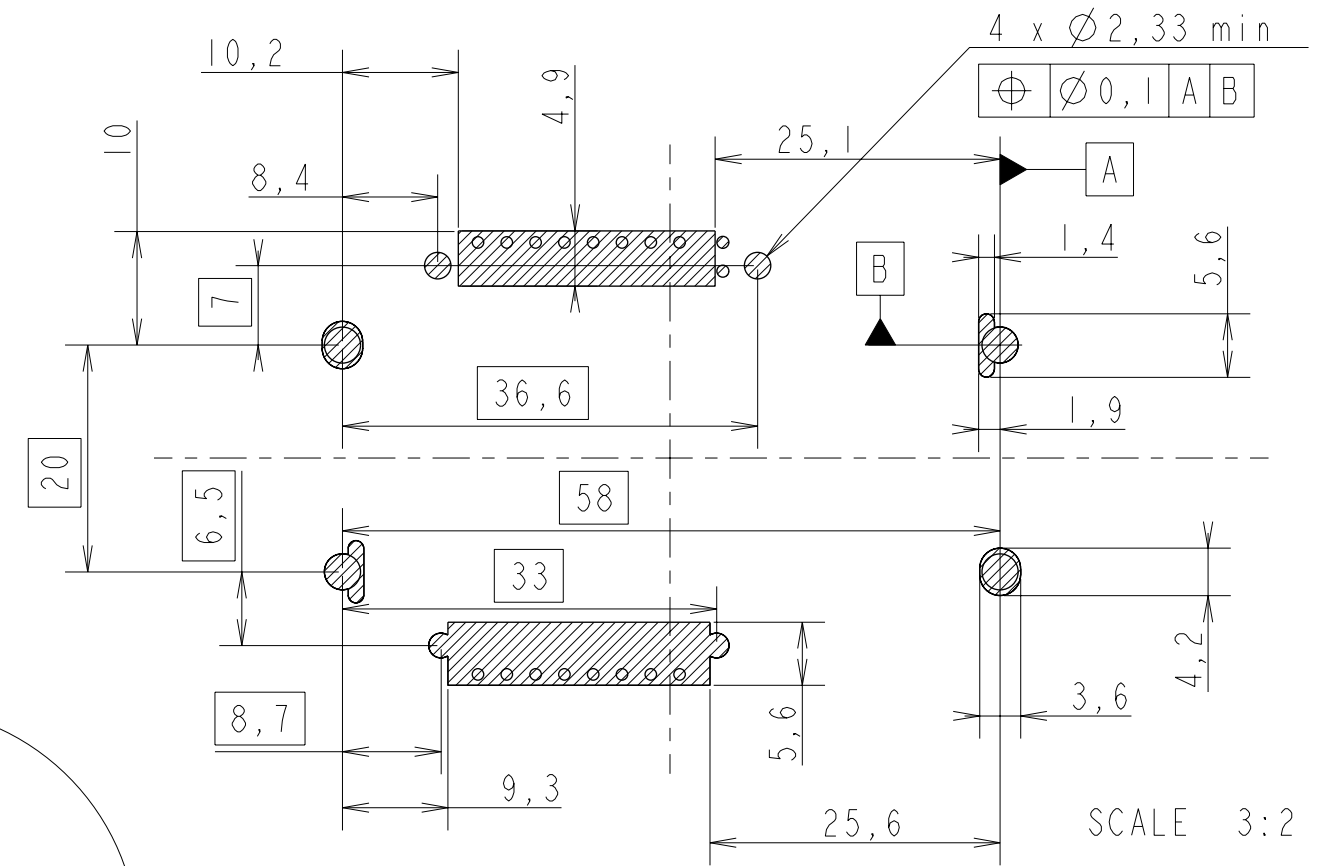
RECOMMENDED PCB LAYOUT

CONTACT CONFIGURATION : ISO & AFNOR
(CONNECTOR SIDE)



SCALE 3:2

STANDARD LAYOUT FOR 'KEEP OUT ZONE' (Connector Side)

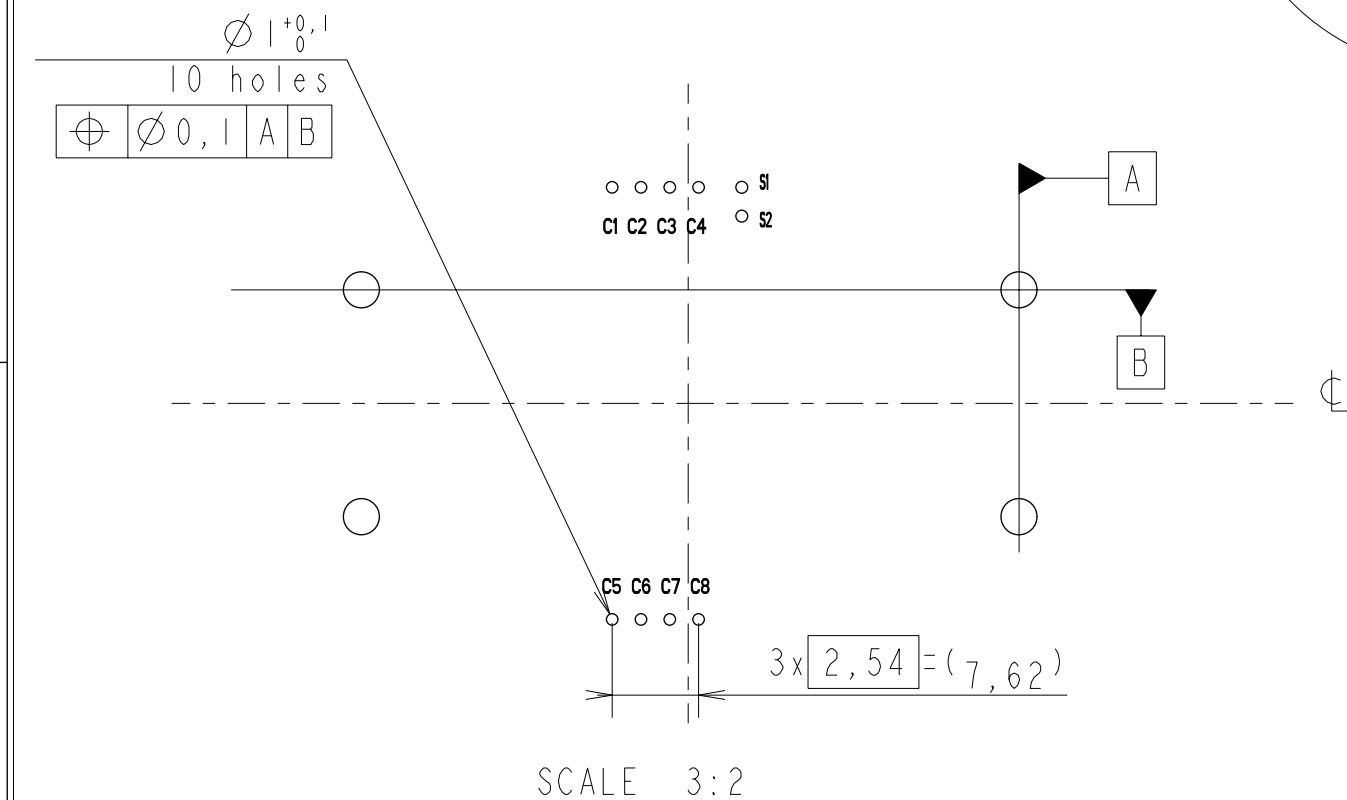


SCALE 3:2

Hatching area might be free of components
Maximum free space outside of these zones = 6.4 mm

RECOMMENDED PCB LAYOUT

CONTACT CONFIGURATION : ISO
(CONNECTOR SIDE)



SCALE 3:2

EUROPEAN PROJECTION

www.fciconnect.com		surface ISO 1302	tolerance std ISO 406 ISO 1101	projection mm
TOLERANCES UNLESS OTHERWISE SPECIFIED				
Dr	N. TWINCY	2002/04/30	ANGULAR	0.X ±
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Chr	RAMESH.P.K	2009/04/15	0° ±°	0.XXX ±
Appr	S.S.CHERIAN	2009/04/15	Product family	SMART CARDS
title L26 TYPE F13			spec ref	SEE NOTES
catalog no			See Table	sheet 2 of 2
dwg no			VJW_54825	Rev. F